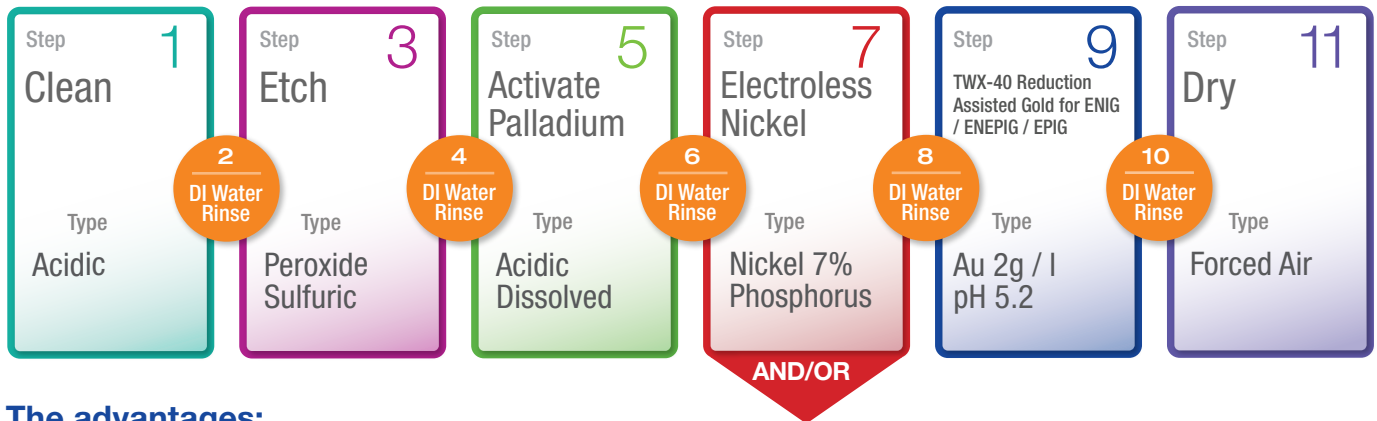


Need Additional Final Finish Capability But Want to Avoid High Capital Costs?

Uyemura has a solution, with chemistry that seamlessly converts an existing ENIG or ENEPIG line into one that's fully capable of processing ENIG, ENEPIG and EPIG.

This is achievable with just a few chemical modifications, and virtually no downtime. There's also an important added benefit: the ability to deposit heavier gold – an increasingly common requirement - while meeting IPC 4552.



The advantages:

- ▶ One line for all three final finishes that are critical to conventional as well as the newer high frequency applications.
- ▶ The ability to process the finer geometries required by higher signal speed.
- ▶ Heavier gold deposition that enhances wire bonding and harsh environment reliability.
- ▶ Enhanced compliance with IPC corrosion specifications.

Step
Electroless Palladium
Type
Palladium 3% Phosphorus

This Uyemura in-line solution creates lucrative new opportunities for board shops and OEMs. Contact your Uyemura representative for details.

UYEMURA INTERNATIONAL CORPORATION



North America's Leading Experts in Final Finishes, Via Fills, Acid and Electroless Coppers, Immersion Silver and Tin; also MEC Surface Treatments and Auruna Gold Electrolytes.

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